




# Power MOSFETS


## PRELIMINARY DATASHEET


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**LM1F098NHP3A**

N-Channel  
Enhancement Mode MOSFET

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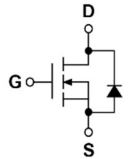
Quality Management Systems

ISO 9001:2015 Certificate

## N-Channel Enhancement Mode MOSFET

### Pin Description

### Product Summary

<b>TO-220-3L (TOP view)</b> 	<b>Symbol</b> 	<b>Symbol</b>	<b>N-Channel</b>	<b>Unit</b>
		$V_{DSS}$	150	V
		$R_{DS(ON)-Max}$	10	m $\Omega$
		ID	111	A

### Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

### Applications

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- DC/DC in Telecoms and Industrial

### Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1F098NHP3A	TO-220-3L	Tube	50 / Tape & Reel	1F098 □□□□□□

Note : □□□□□□ = Lot Code

### Absolute Maximum Ratings (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
$V_{DSS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	±20	
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$I_S$	Diode Continuous Forward Current	T <sub>C</sub> =25°C 114	A
$I_{DM}^{①}$	Pulse Drain Current Tested	T <sub>C</sub> =25°C 277	A
$I_D$	Continuous Drain Current	T <sub>C</sub> =25°C 111	A
		T <sub>C</sub> =100°C 70	
$P_D$	Maximum Power Dissipation	T <sub>C</sub> =25°C 125	W
		T <sub>C</sub> =100°C 50	
$I_D$	Continuous Drain Current	T <sub>A</sub> =25°C 14	A
		T <sub>A</sub> =70°C 11	
$P_D$	Maximum Power Dissipation	T <sub>A</sub> =25°C 2.0	W
		T <sub>A</sub> =70°C 1.3	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.4mH 40	A
$E_{AS}^{③}$	Avalanche Energy, Single pulse	L=0.4mH 320	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State 1	°C/W
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State 62.5	°C/W

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz

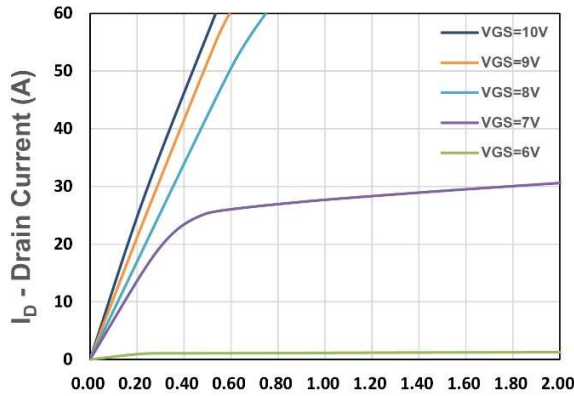
## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics</b>						
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	150	-	-	V
<b>I<sub>DSS</sub></b>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V	-	-	1	uA
<b>V<sub>GS(th)</sub></b>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	2	3	4	V
<b>I<sub>GSS</sub></b>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>R<sub>DS(ON)</sub><sup>④</sup></b>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	8.5	10	mΩ
<b>gfs</b>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>DS</sub> =20A	-	76	-	S
<b>Dynamic Characteristics<sup>⑤</sup></b>						
<b>R<sub>G</sub></b>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Freq.=1MHz	-	1.1	-	Ω
<b>C<sub>iss</sub></b>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =75V, Freq.=1MHz	-	4805	-	pF
<b>C<sub>oss</sub></b>	Output Capacitance		-	366	-	
<b>C<sub>rss</sub></b>	Reverse Transfer Capacitance		-	12.7	-	
<b>t<sub>d(ON)</sub></b>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =75V, I <sub>D</sub> =20A, R <sub>GEN</sub> =10Ω	-	21	-	nS
<b>t<sub>r</sub></b>	Turn-on Rise Time		-	11	-	
<b>t<sub>d(OFF)</sub></b>	Turn-off Delay Time		-	32	-	
<b>t<sub>f</sub></b>	Turn-off Fall Time		-	13.2	-	
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =75V, I <sub>D</sub> =20A	-	57	-	nC
<b>Q<sub>gs</sub></b>	Gate-Source Charge		-	21	-	
<b>Q<sub>gd</sub></b>	Gate-Drain Charge		-	5.6	-	
<b>Source-Drain Characteristics</b>						
<b>V<sub>SD</sub><sup>④</sup></b>	Diode Forward Voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V	-	0.8	1.2	V
<b>t<sub>rr</sub></b>	Reverse Recovery Time	I <sub>F</sub> =20A, V <sub>R</sub> =75V	-	88	-	nS
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/μs	-	176	-	nC

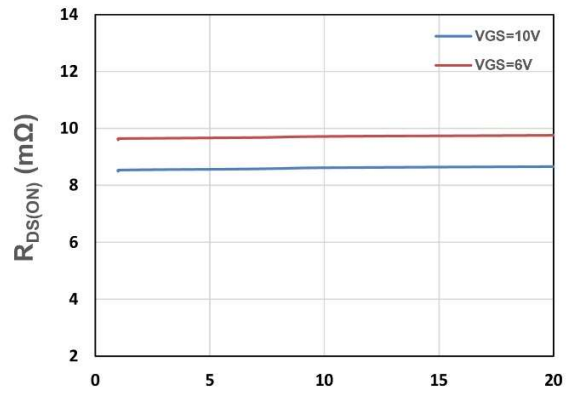
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

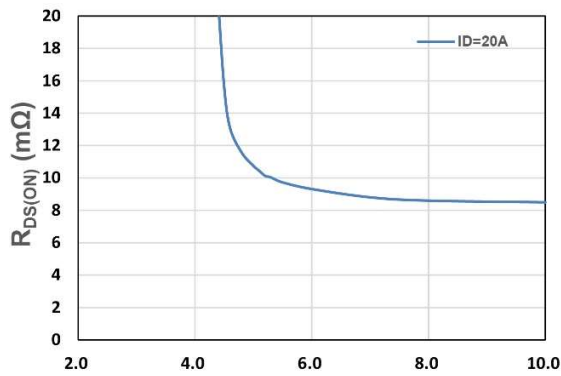
## N-Channel Typical Characteristics



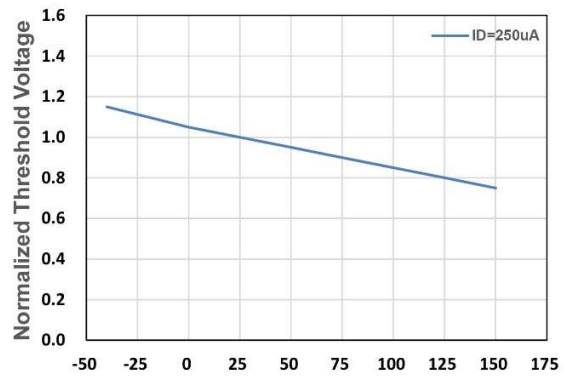
V<sub>DS</sub> - Drain - Source Voltage (V)  
Figure 1. Output Characteristics



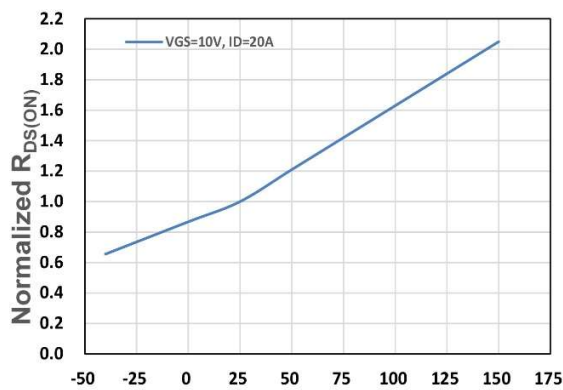
I<sub>D</sub> - Drain Current (A)  
Figure 2. On-Resistance vs. ID



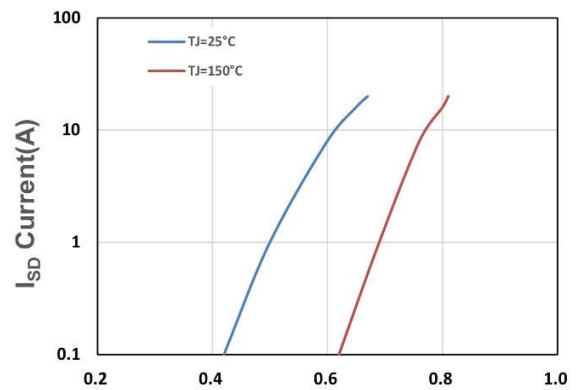
V<sub>GS</sub> - Gate - Source Voltage (V)  
Figure 3. On-Resistance vs. VGS



T<sub>j</sub>, Junction Temperature(°C)  
Figure 4. Gate Threshold Voltage

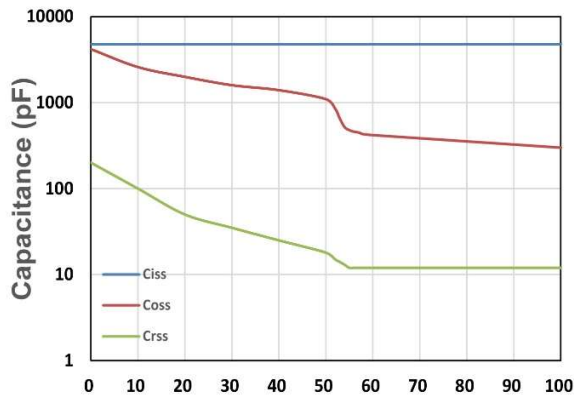


T<sub>j</sub>, Junction Temperature(°C)  
Figure 5. Drain-Source On Resistance

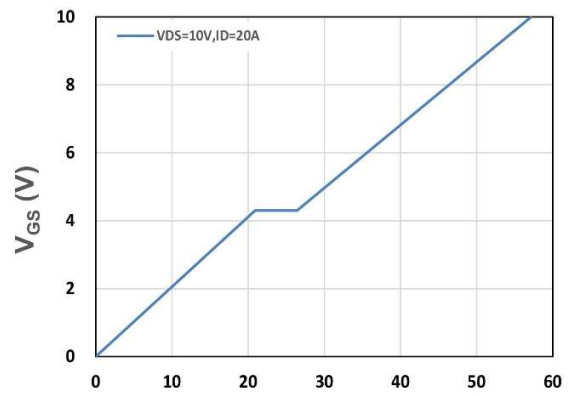


V<sub>SD</sub>, Source-Drain Voltage(V)  
Figure 6. Source-Drain Diode Forward

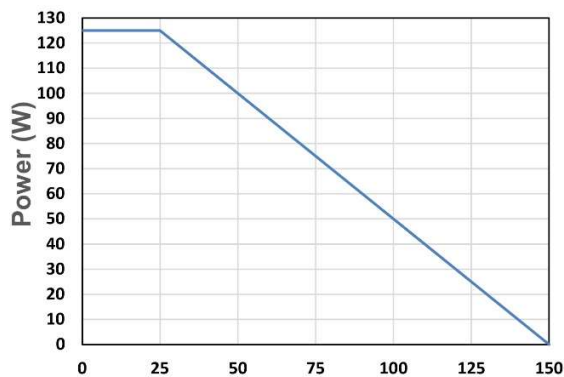
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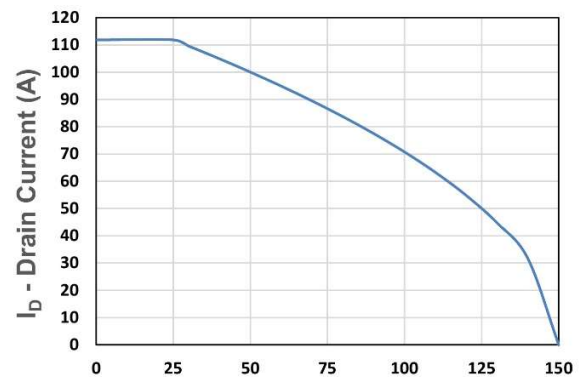
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 7. Capacitance



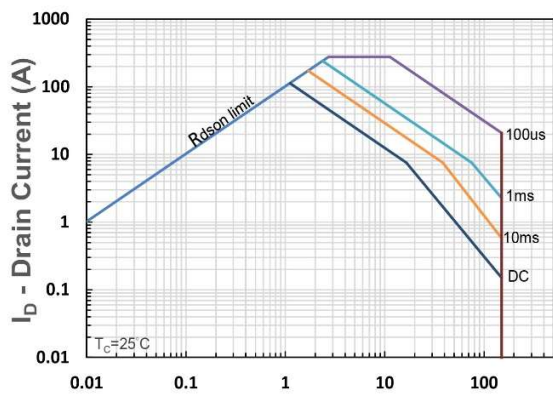
$Q_g$ , Total Gate Charge (nC)  
Figure 8. Gate Charge Characteristics



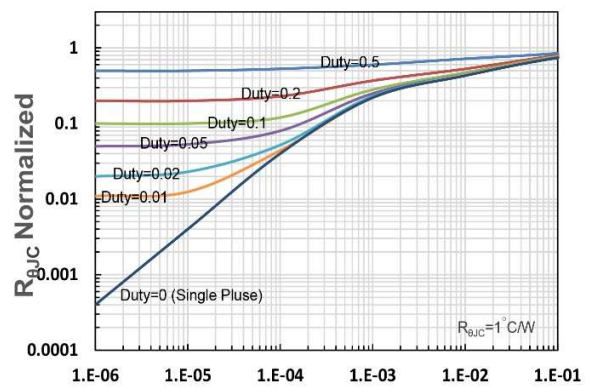
$T_c$  - Case Temperature (°C)  
Figure 9. Power Dissipation



$T_c$  - Case Temperature (°C)  
Figure 10. Drain Current



$V_{DS}$  - Drain-Source Voltage (V)  
Figure 11. Safe Operating Area



$t_1$ , Square Wave Pulse Duration(s)  
Figure 12.  $R_{\theta JC}$  Transient Thermal Impedance